# Low-power interconnection networks

Li-Shiuan Peh Assistant Professor Department of Electrical Engineering Princeton University Why interconnection networks will be of increasing importance...

Systems becoming increasingly parallel...



Why we need low-power interconnection networks...

- 1. Systems are power-constrained due to cooling, power delivery & battery limits.
- 2. Networks consume significant power.



# Outline

- Brief survey of group's research
  - Power-driven network design tools
    - ORION: Architectural network power models
    - LUNA: High-level network power analysis
  - Power-aware networks
    - Dynamic voltage scalable networks
- Thermal modeling and management of on-chip networks
- Next: Network-driven computing

# ORION: Architectural network power models



- Validations: Alpha 21364, IBM InfiniBand switch (close to designers' estimates); MIT Raw (3-11% error)
- Status:
  - Used for network power estimation in CMPs, MPSoCs, network processors in academia and industry
  - 100+ downloads (as of May 2005)

Wang, Zhu, Peh, Malik [MICRO 2002];

Ack: Allen Baum (Alpha 21364), Craig Stunkel (IBM InifniBand switch), Mike Taylor and Anant Agarwal (MIT Raw)

- Link utilization as proxy for node power
  - Input: Message flows between nodes
  - Output: Individual link utilization
- Models contention and backpressure:



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- Link utilization as proxy for node power
  - Input: Message flows between nodes
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- Models contention and backpressure
- Validation: <9% relative error against ORION with up to 2 orders of magnitude speedup
- Status:
  - Used for rapid design space exploration of networks (Intel), compiler power management (Kandemir&Irwin, PLDI'06)
  - Ongoing refinement and validation with Intel
  - □ 50+ downloads



### Dynamic voltage scalable networks

 Explore potential power savings and latency impact



## Dynamic voltage scalable networks

- Explore potential power savings and latency impact
- Design DVS optoelectronic networked system





## Dynamic voltage scalable networks

- 1. Explore potential power savings and latency impact
- 2. Design DVS optoelectronic networked system
- 3. DVS link design
  - Variable-voltage frontend
  - UMC 130nm:
     0.7-1.2V, 4-8Gb/s,
     6.7-40.8 mW





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# Thermal modeling and management of on-chip networks

Shang, Peh, Kumar, Jha [MICRO 2004, TopPicks 2005]

Power and thermal-efficient on-chip networks: A motivating example



#### MIT Raw (0.18um, 300MHz)

First fabricated networked CMP

#### <u>Core</u>:

8-stage in-order single-issue pipeline4-stage single-precision FPU32KB cache32KB software-managed cache

On-chip interconnection network: Four 32-bit 4x4 networks 2 static (8KB software-managed I\$) 2 dynamic Average: 7.2W, Peak: 14.8W 36% of avg chip power

# Methodology



# SIRIUS: Modeling of inter-router thermal correlation

 Capturing heat spreading effect among neighboring components
 Heat spreading angle

 $\theta = \tan^{-1}(k_1/k_2)$ 

Router thermal resistance

$$R = \frac{1}{2k\tan\theta(x-y)}\ln\frac{y+2L\tan\theta}{x+2L\tan\theta}\frac{x}{y}$$

$$R_{i} = R_{i\_silicon} + R_{i\_spreader} + R_{i\_sink} + R_{i\_ambient}$$

$$Thermal \ correlation$$

$$T1 = Q1R1+(Q1+Q2)R3$$

$$T2= Q2R2+(Q1+Q2)R3$$



### SIRIUS: Modeling of On-Chip Links

- Thermal impact of on-chip link circuitry
  - Reduced metal pitch and increased metal layers
  - High thermal resistance of silicon dioxide layers
  - High thermal resistance of low-k insulator materials
- Thermal modeling of on-chip link circuitry
  - Thermal impact of buffers
    - Increased power consumption hence silicon temperature
    - Copper vias have high thermal conductivity
  - Buffer insertion estimation
  - Temperature profile estimation





## Thermal Model Validation

- Modeled actual chip design from IBM
  - In-house finite-element based thermal simulator
  - □ Our model: [70.2, 85.4] °C; IBM: [73.2, 87.8]°C





Chip temperature profile using our thermal model

Estimation error

Thermal characterization of RAW chip



Run-time network thermal management to guarantee safe on-line operation

High spatial and temporal variance in network temperature



#### Thermal design for worst-case no longer cost-effective

ThermalHerd: Let's dynamically steer network traffic to avoid thermal hotspots

- 1. Temperature monitoring
- 2. Traffic estimation & prediction
- 3. Before emergencies
  - Proactive thermal-aware routing
- 4. Upon emergencies
  - Distributed traffic throttling
  - Reactive thermal-aware routing



# ThermalHerd: Thermal Correlation-Based Routing

- Chooses a route based on how thermally correlated it is with the hotspot
  - Hotspot notification messages
  - Pre-computed thermal resistance matrix (based on *Sirius* thermal model) stored at each router
  - Choose minimal path where thermal correlation between source and every hop along the path is < threshold</li>
- Threshold is less aggressive prior to thermal emergencies



# ThermalHerd: Temperature-Aware Traffic Throttling

- How much to throttle?
  - Each router is assigned a quota: number of packets it is allowed to process within a time window
  - Quota reduced exponentially as temperature rises
  - Quota prioritizes local traffic over passing-by traffic
- How to throttle?
  - Disable switch allocation



ThermalHerd evaluation

(Austin TRIPS traces for 16 benchmarks)

Peak temp. without ThermalHerd (94 degrees)



ThermalHerd effectively regulates peak temperature...



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# Network-driven Computing

- Network-Driven Computing
  - Where the on-chip network no longer handles just <u>communication</u>, but also drives all <u>coordination</u> between cores
- Why?
  - Fast access
  - In-transit adaptation
  - Scalable complexity

E.g. in-network cache coherence (poster)



- Sharers kept track of using trees within network routers: Network routes requests to nearest copy.
- Original directory protocol:
  - Requestor (B) to Home Directory (H) to Sharer (A)
- In-network coherence:
  - Enroute from Requestor (B) to Directory (H), network routes request to nearest Sharer (A) and back.
- Scalable:
  - Lessen global traffic
  - Storage overhead scales with number of ports instead of number of cores